

18

OPTICAL SEMICONDUCTOR DEVICE AND ITS ASSEMBLY METHOD

Pat nt Number: JP5055712
Publication date: 1993-03-05
Inventor(s): OMURA ETSUJI
Applicant(s): MITSUBISHI ELECTRIC CORP
Requested Patent: ☐ JP5055712
Application Number: JP19910242767 19910827
Priority Number(s):
IPC Classification: H01S3/18; H01L23/40; H01L33/00
EC Classification:
Equivalents: JP2768852B2

Abstract

PURPOSE: To fix the main surface of the mesa of an optical semiconductor device provided with a mesa groove near an active area to a heat sink material so as to avoid stress concentration in the semiconductor optical device.
CONSTITUTION: This optical semiconductor device 1 is fixed to a heat sink material by using solder 104 only to the main surface of its mesa 106. As a result, the thermal stress applied to an active area 102 from the peripheral section of the element 1 at the time of soldering can be reduced and a semiconductor laser provided with a mesa groove 103 be realized by a semiconductor optical device assembly method which is high in heat radiating effect and high in reliability from the point of service life.

Data supplied from the esp@cenet database - I2